

In the Attorney Docket Number:

Please change the Attorney Docket Number from 50001.31US01/SFI 551 to **35013.5100**.

In the Claims:

Please amend claim 7 to read as follows:

7. (AMENDED) An improvement in an apparatus for orbital polishing of semiconductor wafers to planarize surface of the wafers, the apparatus comprising a pad mounted in a platen, the platen attached to mechanical means for causing the pad to orbit about an axis offset from a central axis of the pad, the pad spaced from carrier to wafer, the carrier coupled to a drive motor to rotate the carrier, and means for pressing a wafer in the carrier forcibly against the pad, the improvement comprising: offsetting the orbital axis from the central axis of the pad by from about 0.05 to about 2.0 mm to cause vibratory motion when the pad orbits.

REMARKS

In his July 12, 2002 Office Action, the Examiner entered a restriction requirement, pursuant to 35 U.S.C. § 121, for the following species of inventions:

- A. Species I, FIG. 2
- B. Species II, FIG. 3
- C. Species III, FIG. 4
- D. Species IV, FIG. 5

In response to the Examiner's restriction requirement, Applicants elect Species I, FIG. 2 (and claims 1-5, 7, 15-23, 25, 27 and 30 relating thereto) for further examination.

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